Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	**Distribute**		
Sectionals *	**Material Info** **Manufacturing Info**	**Subsectionals ***	**A-D** ***: Required Field***

Supplier Information			
Company Name *	**STMicroelectronics**	**Response Date ***	**2018-07-10**
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	**Contact Email ***	Refer to Supplier Comment section
Authorized Representative *	**Rossana Bonaccorso**	**Representative Title**	**ADG MD Champion**
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	**true**	**Legal Declaration ***	**Standard**

Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by rossana bonaccorso
Date: 2018.07.10 15:21:07 +02:00

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STTH30RQ06G2-TR	7T(9*U65Q21I	A	3068	2018-07-10
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	1380.00	mg	Each	ECOPACK1
	Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices		

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
1	245	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
SIP	10.2-7.2-4.5	3	GULL WING	
Comment	H2PAK HC 2-3 Leads			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**TRUE**
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	**Description**
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	**Response**
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**TRUE**
Exemption Id.	**Description**
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			**Response**
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			**FALSE**
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			**TRUE**
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.28	Die- Leadframe	199
Lead	8.04	Soft solder	5827
Antimony trioxide	6.09	Mold compound	4413

QueryList : REACH-15th January 2018				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**7T(9*U65Q21I**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	M-011 Other inorganic materials	7.869	mg	supplier	die	Silicon (Si)	7440-21-3		7.540	mg	958203	5464
				supplier	metallization	Aluminium (Al)	7429-90-5		0.112	mg	14233	81
				supplier	Passivation	Silicon Oxide	7631-86-9		0.037	mg	4702	27
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.004	mg	508	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.013	mg	1652	9
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.061	mg	7752	44
				supplier	polymer die coating	Probimide	Proprietary		0.102	mg	12950	74
Leadframe	M-004 Copper and its alloys	848.009	mg	supplier	alloy	Copper (Cu)	7440-50-8		846.676	mg	998428	613533
				supplier	alloy	Iron (Fe)	7439-89-6		0.848	mg	1000	614
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.254	mg	300	184
				supplier	metallization	Nickel (Ni)	7440-02-0		0.214	mg	252	155
				supplier	metallization	Phosphorus (P)	7723-14-0		0.017	mg	20	12
Soft solder	Solder	8.420	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	8.041	mg	954988	5827
				supplier	solder	Silver (Ag)	7440-22-4		0.211	mg	25059	153
				supplier	solder	Tin (Sn)	7440-31-5		0.168	mg	19953	122
Bonding wires	M-011 Other inorganic materials	4.925	mg	supplier	wire	Aluminium (Al)	7429-90-5		4.925	mg	1000000	3569
Encapsulation	M-011 Other inorganic materials	507.043	mg	supplier	mold compound	Silica, vitreous	60676-86-0		408.676	mg	805999	296142
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		35.493	mg	70000	25720
				supplier	mold compound	Phenol resin	9003-35-4		20.282	mg	40001	14697
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		30.423	mg	60001	22046
				supplier	mold compound	Antimony Trioxide	1309-64-4		6.085	mg	12000	4409
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		3.549	mg	6999	2572
				supplier	mold compound	Carbon black	1333-86-4		2.535	mg	5000	1837
Connections coating	Solder	3.734	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.734	mg	1000000	2706